

**Amendments to the Specification:**

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The system 200 having a first cavity 210, a first plenum 220, a second plenum 230 and a common plenum 240 therein is provided, via step 412. The chassis 200 provided in step 412[[4]] is configured such that the flows determined in step 40[[1]]2-410 can be achieved. In a preferred embodiment, step 412[[4]] also includes providing the system 200 having the modular design described above. Thus, the resultant of the method 400 is, therefore, the system 200 (or the system 100 or 100'). Thus, the method 400 provides a system for packaging a computer system which allows for a high density of components of the computer system while facilitating assembly and servicing.